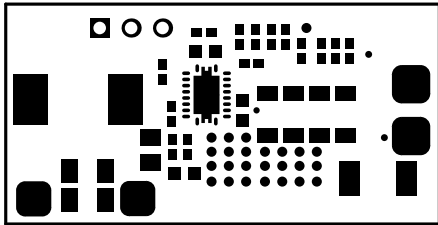
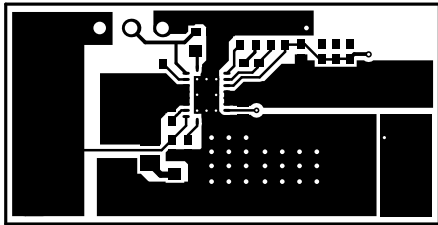


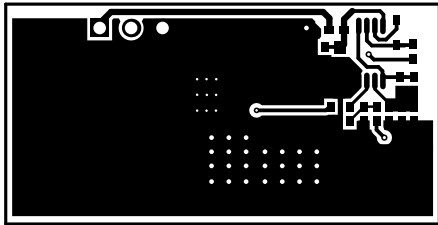
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/23/2016 4:17:54 PM	TEXAS INSTRUMENTS	



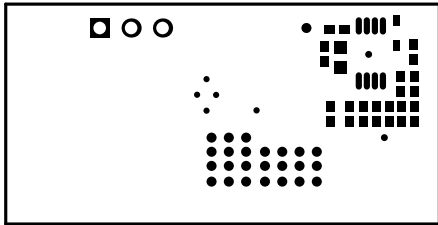
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/23/2016 4:17:55 PM	TEXAS INSTRUMENTS	



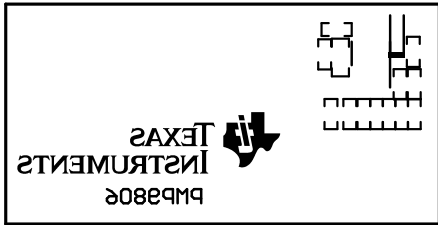
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/23/2016 4:17:56 PM	TEXAS INSTRUMENTS	



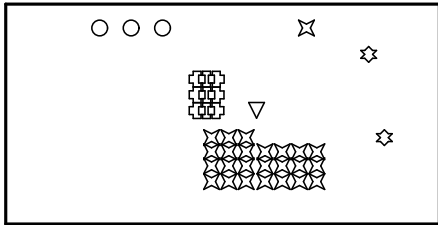
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/23/2016 4:17:57 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/23/2016 4:17:58 PM	TEXAS INSTRUMENTS	

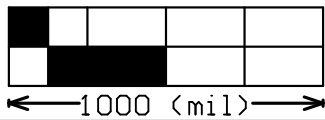
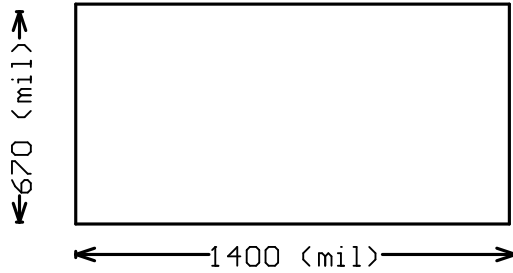


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/23/2016 4:17:59 PM		TEXAS INSTRUMENTS



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
▽	1	8.00mil (0.203mm)	PTH	Round
☆	2	10.00mil (0.254mm)	PTH	Round
○	3	40.00mil (1.016mm)	PTH	Round
⊗	9	7.87mil (0.200mm)	PTH	Round
⊗	25	15.00mil (0.381mm)	PTH	Round
	40 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/23/2016 4:18:00 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9806	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/23/2016 4:18:01 PM	TEXAS INSTRUMENTS	

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